PRODUCT SPECIFICATION

CS1602G-D-FSXTDRN-101

V1.0

February 17, 2009

E Easterntronic LCD Group

REVISION RECORD

REV	Description	Date
V1.0	First Release	Feb 17, 2009

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1. Type Number And Description

Type Number : CS1602G-D-FSXTDRN-101

Description 16 Characters X 2 Lines

LCD Panel FSTN, Negative, Transmissive

Viewing angle 6H

Duty 1/16

Bias 1/5

Operating Temperature: $-20^{\circ}C - 70^{\circ}C$

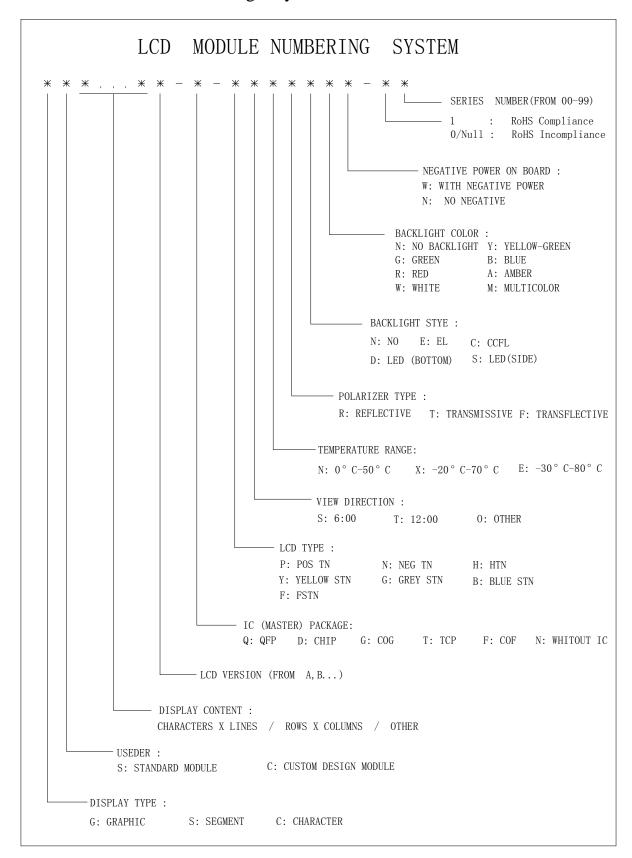
Storage Temperature : $-30^{\circ}C - 80^{\circ}C$

ST7066U-OA Or Equivalent Controller

IC package Bonding

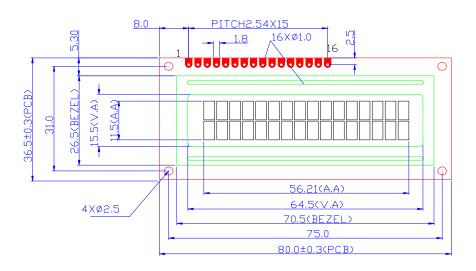
BackLight Red LED, Bottom

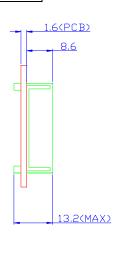
2. LCD Module Numbering System

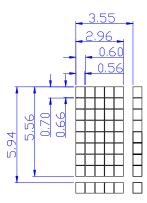


3. Mechanical Specifications

ITEM	STANDARD VALUE	UNIT			
NUMBER OF CHARACTERS	16 CHARACTERS X 2 LINES				
CHARACTER FORMAT	5 X 8DOTS				
MODULE DIMENSION	80.0(W) x 36.0(H) x 13.2(T)	mm			
EFFECTTVE DISPLAY AREA	64.5 (W) x 15.5(H)	mm			
CHARACTER SIZE	2.96(W) x 5.56(H)	mm			
CHARACTER PITCH	3.55 (W) x 5.94(H)	mm			
DOT SIZE	0.56(W) x 0.66(H)	mm			
DOT PITCH	0.6(W) x 0.7(H)	mm			
APPROX WEIGHT	TBD	g			
LCD TYPE	FSTN, TRANSMISSIVE				
DUTY AND BIAS	1/16 DUTY; 1/5 BIAS				
VIEWING DIRECTION	6:00				
BACK LIGHT	Red LED,Bottom				







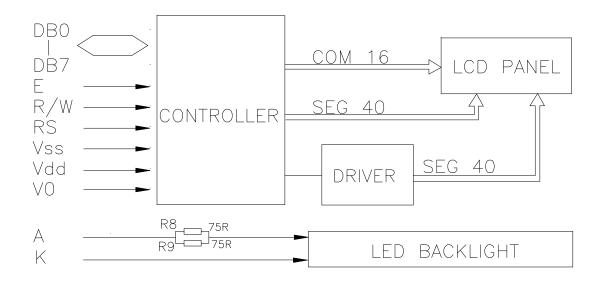
* Remark : General tolerance refers this model. (± 0.2 mm)

4. Electrical Block Diagram

4.1 Pin Definition

PIN	SYMBOL	FUNCTION
1	Vss	Power Supply(GND)
2	Vdd	Power Supply(+5V)
3	Vo	Contrast Adjust
4	RS	Instruction/Data Register Select
5	R/W	Data Read/Write
6	Е	Enable Signal
7-14	DB0-DB7	Data Bus Line
15	K	Power Supply For LED BL(-)
16	A	Power Supply For LED BL(+)

4.2 Electrical Block Diagram



4.3 Display Character Address Code

DISPLAY	POSITION	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
DDRAM	ADDRESS	00	01	02	03	04	05	06	07	08	09	QΑ	OB	00	QD	0E	OF
	MOONE 33	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	40	4E	4F

5. Absolute Maximum Ratings

5.1 Electrical Maximum Ratings(Ta=25deg C)

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

Environmental Conditions 5.2

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	-20	70	deg C
Storage Temp	Ttsg	Dry	-30	80	deg C

6. ELECTRICAL SPECIFICATIONS

Electrical Characteristics at Ta=25 deg C, Vdd = 5V + / - 5%6.1

ITEM	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vss	-	4.5	5	5.5	٧
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V	4.3	4.7	5.0	V
Input signal voltage	V-ih	"H" level	0.7Vdd	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	0.6	V
Supply Current (logic)	Icc	-	0.9	1	1.2	mA
Supply Current (LCD)	lo	-	0.15	0.22	0.27	mA
Supply Voltage (LED)	V-LED	-	3.0	3.4	3.8	V
Supply Current (LED)	lf	-	-	60	200	mA

Timing Specifications at Ta = 25 deg C, Vdd = 5V+/-10%, Vss =0V 6.2

6.2.1 Write mode

ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns

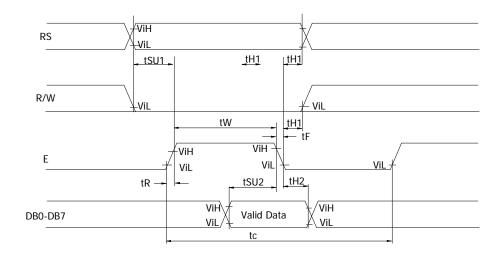
E-pulse width (H, L)	tw	140	ı	ns
R/W and RS set-up time	tsul	0	Ī	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

6.2.2 Read mode

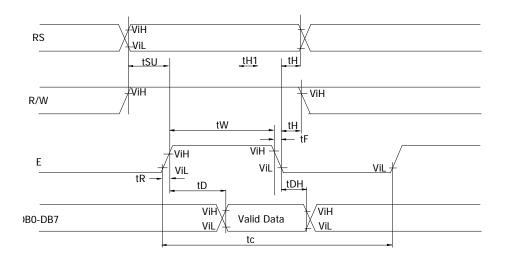
ITEM	SYBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	20	-	ns

6.2.3 Timing Diagram

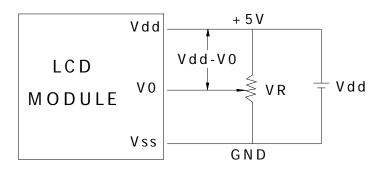
WRITE MODE TIMING DIAGRAM



READ MODE TIMING DIAGRAM



7. Power Supply For LCD Module



Vdd-V0: LCD Driving Voltage

VR: 10K - 20K

8. Electro-Optical Characteristic

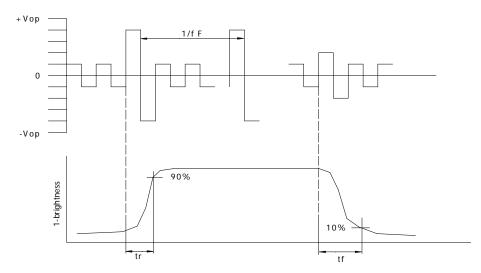
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REF.
Contrast	CR	25℃		12			Note1
Rise Time	tr	25℃		160	240	ms	Note2
Fall Time	tf	25℃		100	150	ms	note 2
Viowing Angle	θ 1- θ 2	25℃			60	DEG	Note 3
Viewing Angle	Ø1, Ø2	25 C	-40		40	DEG	Note 3
Frame Frequency	Ff	25℃		70		Hz	note 2

Note(1): Contrast ratio is defined under the following condition:

- CR= <u>brightness of selected condition</u> brightness of non-selected condition
- (a). Temperature----25C
- (b). Frame Frequency-----64Hz

- (c). Viewing angle----- $\theta = 0$, $\emptyset = 0$
- (d). Operating Voltage---4.7V

Note(2): definition of response time:

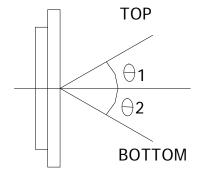


Condition:

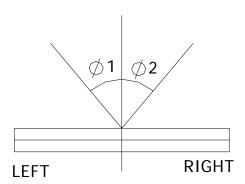
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle----- $\theta = 0$, $\emptyset = 0$
- Operating Voltage---4.7V (d).

Note(3): definition of view angle:

TOP-BOTTOM DIRECTION



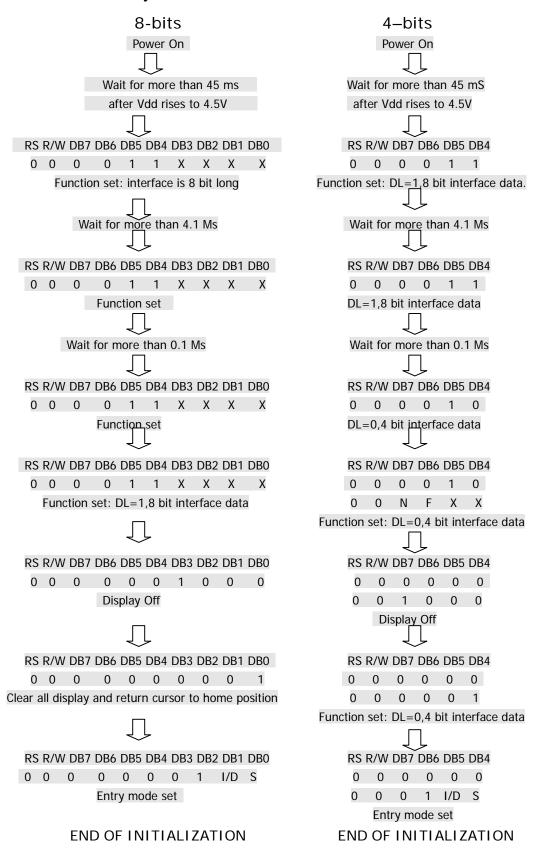
RIGHT-LEFT DIRECTION



9. Instruction Table

Function	R	R	D	D	D	D	D	D	D	D	Description	Execu
							В				•	Time*
							3					(Max)
Clear	0	0									Clears entire display and returns the cursor to	-
Display											home position (address 0)	
Return	0	0	0	0	0	0	0	0	1	Χ	Return the cursor to the home position. DD RAM	1.64mS
Home											contents remain unchanged. Set DD RAM address	
											to zero.	
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40 μ S
mode									/		shift of the display. These operations are	
set									D		performed during data write/read of DD RAM/CG	
											RAM. 1/D=1: increment; 1/D=0: decrement; S=1:	
											whole display shift when data is written.	
Display	0	0	0	0	0	0	1	D	С	В	Set display (D),cursor(C) and blinking of cursor(B)	40 μ S
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.	
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;	
											B=0, Blink OFF.	
Cursor or	0	0	0	0	0	1	S	R	Χ	Χ	Move the cursor and shift the display without	40 μ S
Display								/			changing DDRAM contents. S/C=1: Display Shift;	
shift							С	L			S/C=0:Cursor move. R/L=1:shift to right;	
											R/L=0:shift to left.	
Function	0	0	0	0	1	D	Ν	F	Χ	Χ	Set interface data length (DL), number of display	40 μ S
Set						L					lines (N) and character font (F).DL=1: 8 bits;	
											DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1:	
											5X11 dots; F=0: 5X7 dots.	
Set CG	0	0	0	1			A(CG	i		Set CG RAM address. CG RAM data is sent and	40 μ S
RAM add											received after this setting.	
Set DD	0	0	1			Α	D	D			Set DD RAM address. DD RAM data is sent and	40 μ S
RAM Add											received after this setting.	
Read BF	0	1	В			,	AC	;			Read BUSY FLAG (BF) and the contents of the	0 μ S
& Addr			F								address counter. BF=1: internal operation; BF=0:	
											can accept instruction.	
Write Data	1	0	١	ΝI	RI.	TE	E [ŊΑ	T	4	Write data into DD RAM or CG RAM.	40
to RAM												μ S **
Read Data	1	0		RI	EΑ	D	D	Α	ГΑ		Read data from DD RAM or CG RAM.	40
from RAM												μ S **

10. Initialization By Instruction



11.Software Examples

8-BIT OPERATION 8 characters X 2 lines

Function	RS RW D7 D6 D5 D4 D3 D2 D1 D0	DISPLAY	DESCRIPTION
Power on delay		Initialization. No display appears.	
Function set	0 0 0 0 1 1 0 0 X X		Sets 8-bit operation, 2-line display and 5*7
			dots character font.
Display OFF	0 0 0 0 0 0 1 0 0 0	-	Turn off display.
Display ON	0 0 0 0 0 0 1 1 1 0	-	Turn on display and cursor.
Entry Mode set	0 0 0 0 0 0 0 1 1 0		Set mode to increment the address by one
			and to shift the cursor to the right, at the
		1	time of write to the DD/CG RAM. Display
		i	is not shifted.
Write data to	1 0 0 1 0 0 1 1 1 1	O\	Write "O". Cursor incremented by one and
CG/DD RAM			shift to right.
Write data to	1 0 0 1 0 1 0 0 1 0	OR\	Write "R". Cursor incremented by one and
CG/DD RAM			shift to right
Write data to		ORIENT	Write "I" "E" "N" "T".
CG/DD RAM			
Set DDRAM	0 0 1 1 0 0 0 0 0 0	ORIENT S	Set RAM address so that the cursor is
address		I	positioned at the head of the Second line
Write data to		<u>ORIENT</u>	Write "D" "S".
CG/DD RAM		DS	
Cursor or display	0 0 0 0 0 1 0 0 X X	ORIENT S	Shift only the cursor position to the left.
shift		DS	
Write data to		ORIENT	Write "I" "S" "P" "L" "A" "Y"
CG/DD RAM		DISPLAY	

4-bit operation (4-bits 1 line)

Function	RS	RW	D7	D6	D5	D4	Display	Description	
power on delay								Initialization. No display appears.	
Frnction set	0	0	0	0	1	0		Sets to 4-bit operation. In this case, operation is handle as 8-bits by initialization,a nd Only this instruction completes with one write.	
Frnction set	0	0	0	0	-	0 X		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fontscannot be changed hence after.)	
Display ON/OFF Control		0	0 1	0	0			Turn on display and cursor.	
Entry Mode Set	0	0	0	0	0			Turn on display and cursor.	
Write data to CG/DD/ARM	1 1	-	0 1	1 1	0			Write "O". Curaor incrementer by one and shift to right.	
						9	same as 8-bi	t operation	

12.Quality units

12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

12.2 Scope

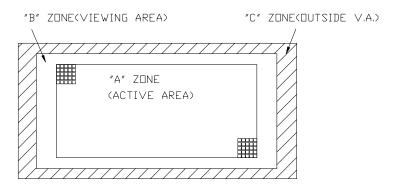
This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

12.3 Definition

12.3.1 Definition of area

A Zone: Active area. B Zone: Viewing area

C Zone: Outside viewing area.



12.3.2 Definition of size

Large size(L): 1~6 pcs LCD screens are cut out of from each 14"×16" mother glass. Middle size(M): $7 \sim 50$ pcs LCD screens are cut out of from each $14" \times 16"$ Small size(S): more than 50 pcs LCD screens are cut out of from each 14"×16" glass.

12.4 Quality Specification

12.4.1 Conditions of Cosmetic Inspection

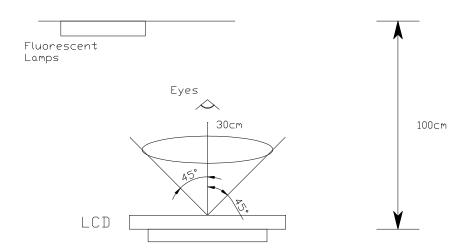
12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 \pm 5°C. Ambient humidity: $65 \pm 20\%$ RH

Ambient Luminance: 40-watt fluorescent lamp.

An appearance test should be conducted by human sight at approximately 30 cm distance

from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.
- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

12.4.4 Applicable instrument

- LCD module tester
- Multimeter
- Caliper
- Defect size filming standard

12.4.5 Inspection quality criterion

12.4.5.1 LCD panel part

The inspection specification as following list:

Classify	Item	Description of defects	Inspection criterion			Drawing Decification
Major defect	1.Non-display	Product no function	Not	accept	5]	ecilication
	2.LCD with wrong view direction`	Difference in Spec.	Not	Not accept		
	3.Segment missing	Part or all pattern do not light up	Not	accept		
	4.Occur high current	Current exceed designed value	Not	accept		
	5. LC leakage	LC does not fulfill the glass cell	Not	accept		
	6.Deviation from drawing	LCM Dimension difference from drawing and over tolerance	According to dimensions noted in the specification			
	7.Wrong type applied	Wrong polarizer attachment	Not	accept		
		Pin attached wrong type applied	Not	accept		
	8.Incorrect pins quality	Pin attached wrong quantity applied	Not accept			
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1	Acceptable number Not count (Should not be connected to next dot)		A A

			0.10 <a≤0.15 B≤0.10</a≤0.15 	1 pc / dot(only segment) or less 2 pcs / cell or less (Should not be connected to next dot) Not count	
Minor	10.Pinholes	Black spot/white	1. large size		
defect		spot at activated	_	n't be found at	
		state		e and will not	
			_	er electronic test	
			2. Middle si		Y
			Diameter(min $\Phi \le 0.15$	n) Accept QTY Not count	→
			$\Phi \le 0.15$ $0.15 < \Phi \le 0.25$		X
			$0.15 < \Phi \le 0.25$ $0.25 < \Phi \le 0.35$		$\Phi = (X+Y)/2$
			$\Phi > 0.35$		- (1111)/2
			3. Small siz		
			Diameter(mn	n) Accept QTY	
			Φ≤0.15	Not count	
			0.15<Φ≤0.25	2	
			$0.25 < \Phi \le 0.30$	1	
			$\Phi > 0.30$		
			4. For the	*	
				f the area of	
				s less than or	
			-	half of one	
			lattice's	w one defect in	
			one segm		
			6. The ne		
				between two	
			pinholes		
			Remarks:	Regarding the	
			product in	negative type	
			_	STN and FSTN),	
				riving voltage, the	
				should be less or	
			_	$\Phi \leq 0.2$). If the	
				e is lower 0.3V	
			man the norma	l voltage, it should	

		be abnormal voltage, it can not	
		judge the white dot base on	
		abnormal voltage.	
		achormar voltage.	
11.Blemishes	Black spot/dust	Positive panel:	•
and foreign	on	1.A zone	
matters	LCD(non-display	- Large size LCD	
)	Accept if can't find at 1m	
		distance and will not enlarge	
		under electronic test:	$\Phi = (X+Y)/2$
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		Φ≤0.15 Not count	
		$0.15 < \Phi \le 0.25$ 3	
		$0.25 < \Phi \le 0.35$	
		$\Phi > 0.35$ 0	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		Φ ≤ 0.15 Not count	
		$0.15 < \Phi \le 0.25$ 2	
		$0.25 < \Phi \le 0.30$ 1	
		$\Phi > 0.30$ 0	
		2.B zone	
		1.5 times of acceptable	
		largest diameter size of Zone	
		A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		0.15<Φ≤0.30 4	
		0.30<Φ≤0.50 1	
		$\Phi > 0.50$ 0	
		-Middle&small size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		0.15<Φ≤0.25 3	
		$\Phi > 0.25$ 0	
		2. B zone	
		1.5 times of acceptable	

largest diameter size of Zone A 3.C zone No count The nearest diatance allowed between two black spot is	
20mm	

	T		
12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	L L
scratches	surface.And	- Large size LCD	
	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		W≤ 0.02 Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 3$ 2	
		$0.02 < W \le 0.03, L > 4 $ 0	
		$0.03 < W \le 0.05, L > 3 0$	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		W≤ 0.02 Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$	
		$0.02 < W \le 0.03, L > 4 $ 0	
		$0.03 < W \le 0.05, L > 2 0$	
		W>0.05 As the spot criteria.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative nanel	
		Negative panel:	
		1. A zone	
		-Large size LCD	

			Diameter(mm) Accept QTY	
			W≤ 0.02 Not count	
			0.02< W≤ 0.03,L ≤5 3	
			$0.03 < W \le 0.05, L \le 4$ 2	
			0.02< W≤ 0.03,L >5 0	
			$0.03 < W \le 0.05, L > 4 $ 0	
			W>0.05 As the spot criteria.	
			Middle des LCD	
			-Middle size LCD	
			Diameter(mm) Accept QTY	
			$W \le 0.02$ Not count	
			0.02< W≤ 0.03,L ≤4 2	
			$0.03 < W \le 0.05, L \le 2$	
			0.02< W≤ 0.03,L >3 0	
			$0.03 < W \le 0.05, L > 2 $ 0	
			W>0.05 As the spot criteria.	
			-Small size LCD	
			Diameter(mm) Accept QTY	
			$W \le 0.02$ Not count	
			0.02< W≤ 0.03,L ≤3 2	
			$0.03 < W \le 0.05, L \le 3$	
			0.02< W≤ 0.03,L >3 0	
			$0.03 < W \le 0.05, L > 2 $ 0	
			W>0.05 As the spot criteria.	
			2. B zone	
			1.5 times of acceptable largest	
			diameter size of Zone A	
			3.C zone	
			Not count	
			The nearest diatance allowed	
			between two defects is 20mm	
Mintor	13. Scratch	PI coating	The visible scratch of A zone can	
defect	on PI coating	scratched	not be accepted at 30cm view	
			distance.	
Mintor	14. Rainbow	Arches,circular	According to the limit specimen	
defect		or parallel		
		colorful spread		

Mintor	15. Bubbles	Bubbles or	A zone:	The visibl	e defect	can not	
defect	or wrinkles in	wrinkles	be accepted at 30cm view				
	polarizer	between	distance.				
		polarizer and	B zone: Not count				
Minter	16 Danidian	glass	D-1	4 1'			
Mintor	16. Position	Wrong polarizer attachment in		r protrudi	_	_	
defect	of polarzer attachment		_	nd excee m externa	_		
	attaciiiieit	position or dimension	LCD	iii externi	ai dilliei	ision of	
Mintor	17. Ink	17.1 Ink	Not acce	nt			
defect	printing	line/pattern	1 voi accc	·ρι			
derect	defect	broken					
	derect	17.2 Ink	Accept i	f the thic	k or thi	n part is	
		pattern/line	_	equal to		-	
		jagged		r accordi		_	
		3 88	specime		U		
		17.3 Light	When	activated	with	current	
		leakage	white lig	ht appear	s in the	position	
			of pinho	le or scr	atch due	e to ink	
			printing	misalign	ment.Ac	ccording	
			to the pin	nhole spe	cificatio	n.	
		17 4 Iuly minting	Dainat if	41a a 41a a 1	412	:	
		17.4 Ink printing pattern/line	than 1/2	the thick	or unin	m more	
		uneven		w. hen W1-	W/2~1/3V	X/	<u> </u>
		uneven	Reject w	nen w 1-	VV 251/3	**	W1 W2
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomi	ng	defect:	`
defect		or foreign	oxidized	,damage(includin	g pins	
		material on	plating	damaged),excess	epoxy	
		terminal legs	on bott	om glas	ss or	terminal	
			legs.Not				
		18.2 Pin	According to the specification				
		deviation over					
		tolerance		T .	1	1	
Mintor	19. Chipped	19.1 Chip in	a	b	c	accept	
defect	glass on	lead contact		1		QTY	
	comer	area.	a≤5mm	b≤W	c≤T		
			L>5m			3	
			m o < I	haw	0.CT	3	
			a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
			L<5m				
i			L<5m				

		19.2 Others	Mot exc width of		c≤T	3	ITO V
Mintor							
defect	20. Glass	chip on edge	a	b	С	accept QTY	1 × 2 0
			a≤5mm	Not exceed 1/2 width of seal	c≤T	3	C
Mintor	21. Clipped electrode pad	21.1Glass chip on ITO edge	a	b	С	accept QTY	ITO
defect			a≤4mm (and not exceed 4 ITO termina 1	b≤W/4	c≤T	3	
		21.2 Glass chip on ITO back	a	b	c	accept QTY	0, 0,
		3 2.2.3 Such	a≤5mm	b≤W/3	c≤T	3	
Mintor defect	22. Mechanical	Extended crack inspector shall	b	1	accept	QTY	0 W

	damage	attempt to remove the chip	b≤W/4	2	
		with			
		tweezers,re-eval			<u>→</u>
		uate if the			
		remaining defect			
		is still a crack or			
		a chip			
Mintor	23.Glass cracks		Not accept		
defect					

Remark:

The minimum space between any 2 defects(spot,dirt) should more than 20mm, and max. allowed defect QTY in total:

Large size LCD: Zone A≤ 5/unit, Zone B≤ 5/unit; Middle size LCD: Zone $A \le 3/unit$, Zone $B \le 3/unit$; Small size LCD: Zone A≤ 2/unit, Zone B≤ 2/unit;

12.4.5.2 Other part

The inspection specification as following list:

NO.	Items	Criterion of defects	AQL		
1	Backlight	 Lumination source flickers. Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight. 			
		3. Not allow unlighted on backlight.			
		4. Colour and luminance of backlight should correspond its specification.	Major Major		
2	PCB,COB	1.COB seal may not have pinholes larger than 0.2mm or contamination.2.COB seal surface may not have pinholes through to the IC.			
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major		
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.			
		5.No oxidation or contamination on PCB connector.			
		6.Parts on PCB should correspond the characteristic, and not allow wrong parts, missing parts or additional parts.			
		7.The jumper on the PCB should correspond to the characteristic.			
		8. The solder which gets on bezel, LED pad, zebra pad or screw hole pad should be smoothed down.			
		1. No unmelted solder pastes on the PCB.	Minor		
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor		
		3. No short circuits in components on PCB.	Minor		
4	General 1. No oxidation, contamination, curves, cracks or bends interface Pin of TCP.		Minor		
		2. No solder residue or solder balls on product.	Minor		
		3. The IC on TCP may not be damaged.	Major		
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor		
		5. Packing method correspond the specification.	Major		
		6. Dimension and structure correspond the specification sheet.	Major		
		7. No dirt and break on the heat seal.	Major		

12.5 Reliability

The LCD module shall not fail the following reliability test.

Item	Condition		Criterion
High temperature	$+70^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 8 hours		
operation			
Low temperature	-20°C ±2°C, 8 hours		1.Total current
operation		consumption	
Humidity	Operation	$40^{\circ}\text{C} \pm 2^{\circ}\text{C},93\% \pm 2\%\text{RH,8}$	should be below
		hours	double of initial
	Storage	$40 ^{\circ}\text{C} \pm 2 ^{\circ}\text{C},93\% \pm 2\% \text{RH},$	value.
		24 hours	2.Cosmetic defects
High temperature	$+80^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 10 hours		should not be
storage			happened
Low temperature	-30°C ±2°C, 10 hours		
storage			
Thermal shock	-20°C ~ +70°C		
storage	60min~60min, 5 cy		
Vibration test	Amplitude:0.7~1.0		
	in each direction(X		
Shock test	To be measured aft		
	80cm high on the c		
	state.(weight≥15K		
	Weight<15Kg,dro		
		Dropping method corner dropping	
	<u> </u>	D A corner: once	
	G	Edge dropping B,C,D edge: once	
	D	Free describe	
	60/8	80cm E,F,G face: once	
		Concrete Surface	
	///////////////////////////////////////		

Remark: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.

13. Precaution For Using LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The precautions should be taken when handing,

- (1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.
- (2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.
- Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.
- (4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.
- (5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

- (1). Do not tamper in any way with the tabs on the tabs on the metal frame.
- (2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.
- (3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).
- (4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- (5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

- (2). The modules should be kept in antistatic bags or other containers resistant to static for storage.
- (3). Only properly grounded soldering irons should be used.
- (4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.
- (5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.
- (6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.
- 2.3. Soldering
- (1). Solder only to the I/O terminals.
- (2). Use only soldering irons with proper grounding and no leakage.
- (3). Soldering temperature: 280 $^{\circ}\text{C} \pm 10^{\circ}\text{C}$
- (4). Soldering time: 3 to 4 sec.
- (5). Use eutectic solder with resin flux fill.
- (6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

- (1). The viewing angle can be adjusted by varying the LCD driving voltage V0.
- (2). Driving voltage should be kept within specified range; excess voltage shortens display life.
- Response time increases with decrease in temperature.
- Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
- (5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above. EASTERNTRONIC will not responsible for any subsequent or consequential events.

14. Declaration of conformity regarding the limitation of dangerous substances

深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R.China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS1602G-D-FSXTDRN-101 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

- Lead
- Mercury
- Cadmium
- Hexavalant chromium
- Polybrominated biphenyls
- Polybrominated diphenylethers

And to the annex which points out the exempted implementations \square To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

- 0ils containing polychlorinated biphenyl
- Asbestos
- Radioactive substances

Name: Ding

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on Feb 17, 2009

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.